

SK50GAL067



IGBT Module

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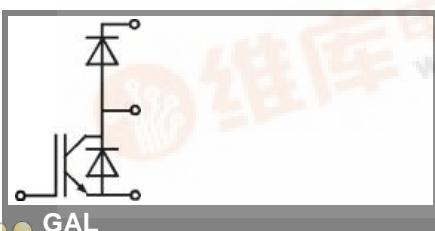
Target Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Hyperfast NPT technology IGBT
- N-channel homogeneous silicon structure (NPT Non-Punch-Through IGBT)
- Positive $V_{ce,sat}$ temperature coefficient (Easy paralleling)
- Low tail current with low temperature dependence
- Low threshold voltage

Typical Applications

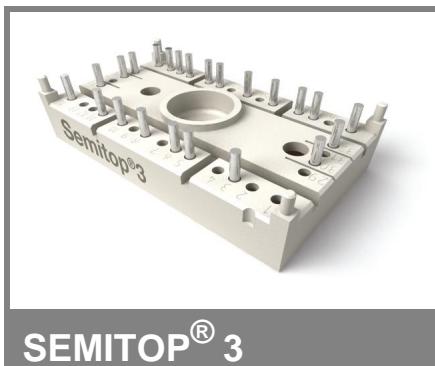
- Switching (not for linear use)
- High Frequencies Applications
- Welding generator
- Switched mode power supplies
- UPS



Symbol		Conditions	$T_s = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions		Values	Units	
IGBT					
V_{CES}	$T_j = 25^\circ\text{C}$		600		V
I_C	$T_j = 125^\circ\text{C}$	$T_s = 25^\circ\text{C}$	83		A
		$T_s = 80^\circ\text{C}$	54		A
I_{CRM}	$I_{CRM} = 2 \times I_{Cnom}$		240		A
V_{GES}			± 20		V
t_{psc}	$V_{CC} = 300\text{ V}$; $V_{GE} \leq 20\text{ V}$; $T_j = 125^\circ\text{C}$ $V_{CES} < 600\text{ V}$		10		μs
Inverse Diode					
I_F	$T_j = 125^\circ\text{C}$	$T_s = 25^\circ\text{C}$	90		A
		$T_s = 80^\circ\text{C}$	56		A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$				A
I_{FSM}	$t_p = 10\text{ ms}$; sinusoidal	$T_j = {}^\circ\text{C}$	360		A
Freewheeling Diode					
I_F	$T_j = 125^\circ\text{C}$	$T_{case} = 25^\circ\text{C}$	90		A
		$T_{case} = 80^\circ\text{C}$	56		A
I_{FRM}	$I_{FRM} = 2 \times I_{Fnom}$				A
I_{FSM}	$t_p = 10\text{ ms}$; sinusoidal	$T_j = {}^\circ\text{C}$	360		A
Module					
$I_{t(RMS)}$					A
T_{vj}			-40 ... +150		${}^\circ\text{C}$
T_{stg}			-40 ... +125		${}^\circ\text{C}$
V_{isol}	AC, 1 min.		2500		V

Symbol		Conditions	$T_s = 25^\circ\text{C}$, unless otherwise specified		
Symbol	Conditions		min.	typ.	max.
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 1,2\text{ mA}$		3	4	5
I_{CES}	$V_{GE} = 0\text{ V}$, $V_{CE} = V_{CES}$	$T_j = 25^\circ\text{C}$			0,008
I_{GES}	$V_{CE} = 0\text{ V}$, $V_{GE} = 20\text{ V}$	$T_j = 25^\circ\text{C}$			480
V_{CE0}		$T_j = 150^\circ\text{C}$			2
r_{CE}	$V_{GE} = 15\text{ V}$	$T_j = 150^\circ\text{C}$			$\text{m}\Omega$
$V_{CE(sat)}$	$I_{Cnom} = 120\text{ A}$, $V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}_{\text{chiplev.}}$	2,8	3,15	V
		$T_j = 125^\circ\text{C}_{\text{chiplev.}}$	3,5	4	V
C_{ies}			6		nF
C_{oes}	$V_{CE} = 25$, $V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$	0,6		nF
C_{res}			0,37		nF
$t_{d(on)}$			22		ns
t_r	$R_{Gon} = 6\text{ }\Omega$	$V_{CC} = 400\text{ V}$	10		ns
E_{on}		$I_{Cnom} = 120\text{ A}$	2,7		mJ
$t_{d(off)}$	$R_{Goff} = 6\text{ }\Omega$	$T_j = 125^\circ\text{C}$	280		ns
t_f		$V_{GE} = \pm 15\text{ V}$	26		ns
E_{off}			1,9		mJ
$R_{th(j-s)}$	per IGBT			0,45	K/W

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Typical Applications

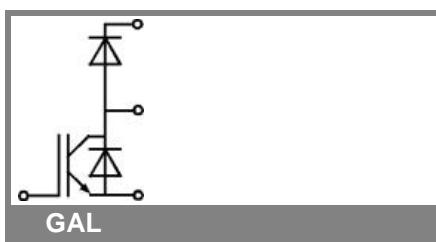
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- High Frequencies Applications
- Welding generator
- Switched mode power supplies
- UPS

Characteristics

Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 120 \text{ A}$; $V_{GE} = 0 \text{ V}$ $T_j = 25 \text{ }^\circ\text{C}_{\text{chiplev.}}$ $T_j = 125 \text{ }^\circ\text{C}_{\text{chiplev.}}$		2 1,25		V V
V_{F0}	$T_j = 25 \text{ }^\circ\text{C}$ $T_j = 150 \text{ }^\circ\text{C}$		1		V V
r_F	$T_j = 25 \text{ }^\circ\text{C}$ $T_j = 150 \text{ }^\circ\text{C}$		4		$\text{m}\Omega$ $\text{m}\Omega$
I_{RRM} Q_{rr} E_{off}	$I_{Fnom} = 120 \text{ A}$ $\text{di/dt} = -100 \text{ A}/\mu\text{s}$ $V_R = 600\text{V}$	$T_j = 125 \text{ }^\circ\text{C}$			A μC mJ
$R_{th(j-s)D}$	per diode			0,8	K/W
Freewheeling Diode					
$V_F = V_{EC}$	$I_{Fnom} = 120 \text{ A}$; $V_{GE} = 0 \text{ V}$ $T_j = 25 \text{ }^\circ\text{C}_{\text{chiplev.}}$ $T_j = 125 \text{ }^\circ\text{C}_{\text{chiplev.}}$		2 1,25		V V
V_{F0}	$T_j = 25 \text{ }^\circ\text{C}$ $T_j = 150 \text{ }^\circ\text{C}$		1		V V
r_F	$T_j = 25 \text{ }^\circ\text{C}$ $T_j = 150 \text{ }^\circ\text{C}$		4		V V
I_{RRM} Q_{rr} E_{off}	$I_{Fnom} = 120 \text{ A}$ $\text{di/dt} = -100 \text{ A}/\mu\text{s}$ $V_R = 600\text{V}$	$T_j = 125 \text{ }^\circ\text{C}$			A μC mJ
$R_{th(j-s)FD}$	per diode			0,8	K/W
M_s	to heat sink	2,25	2,5		Nm
w			29		g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

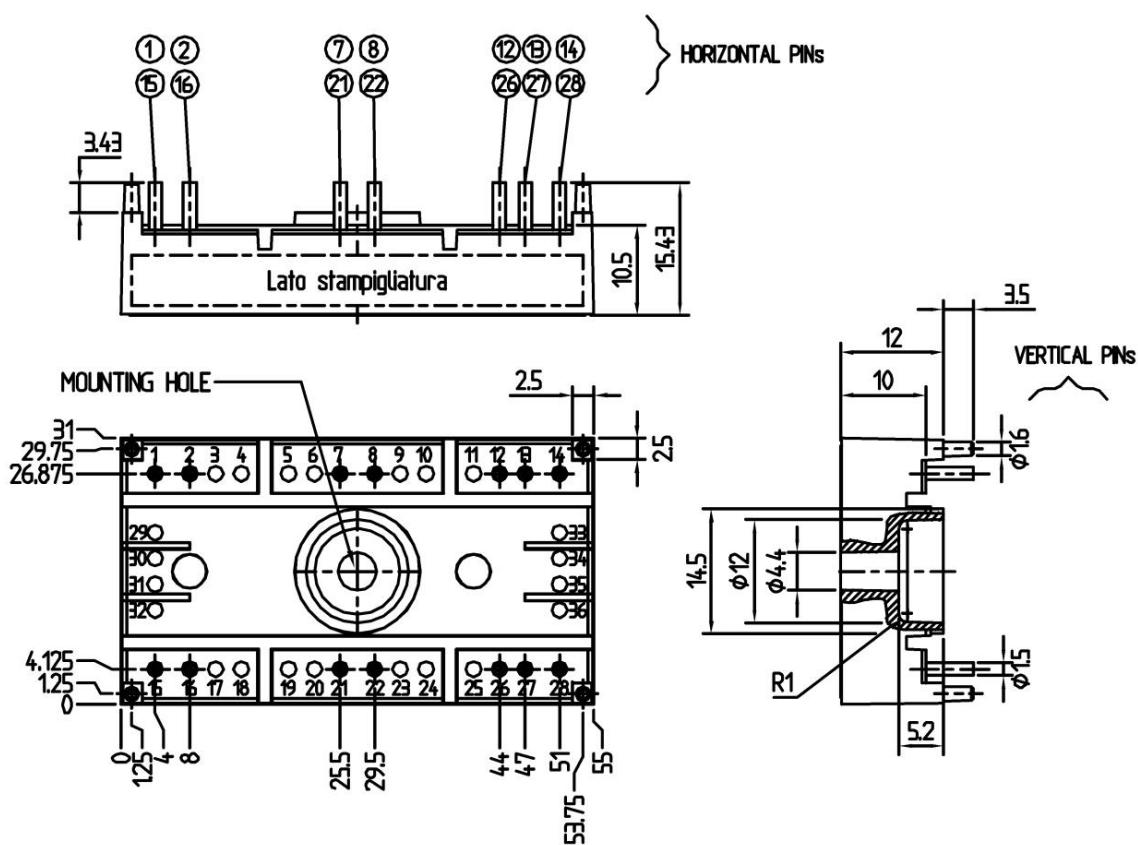
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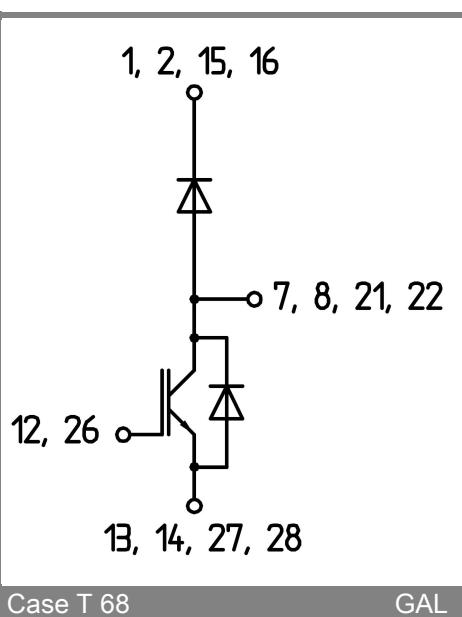
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UL Recognized
File no. E 63 532

Dimensions in mm



Case T68 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T 68

GAL